

# SOT1068-1

plastic thermal enhanced ultra thin quad flat package; no leads; 16 terminals; UTLP based; body 3 x 3 x 0.55 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HUQFN16U
<b>Package type industry code</b>	HUQFN16U
<b>Package style descriptive code</b>	HUQFN (thermal enhanced ultra thin quad flatpack; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	26-2-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	0.5	-	0.55	0.6	mm
A <sub>2</sub>	package height	[tbd]	-	0.55	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	16	-	

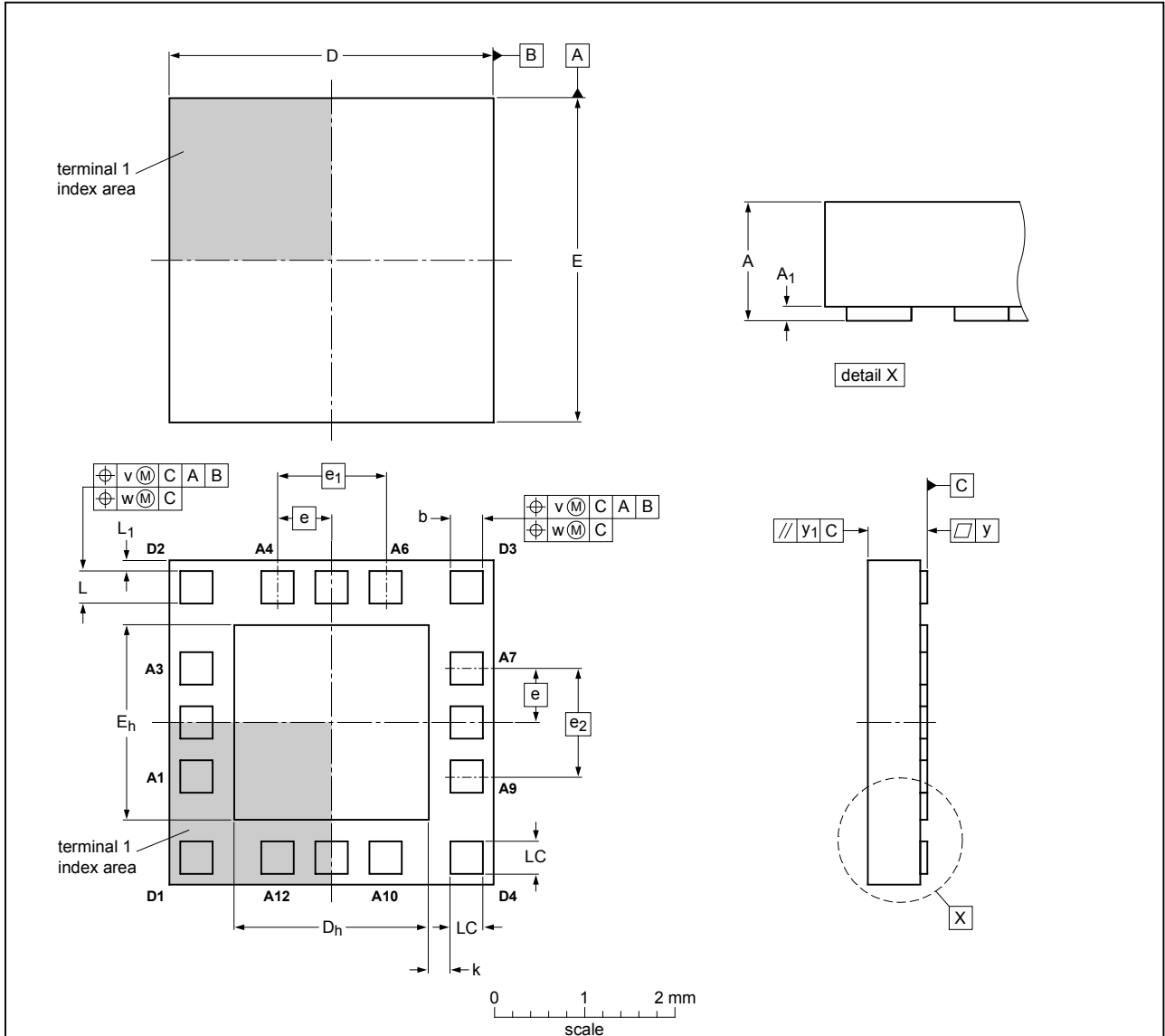


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## 2. Package outline

HUQFN16U: plastic thermal enhanced ultra thin quad flat package; no leads; 16 terminals; UTLP based; body 3 x 3 x 0.55 mm

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DIMENSIONS (mm are the original dimensions)

UNIT		A	A <sub>1</sub>	b	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	LC	L <sub>1</sub>	k	v	w	y	y <sub>1</sub>
mm	max	0.60	0.10	0.35	3.1	1.85	3.1	1.85	0.5	1	1	0.35	0.35	0.13	0.23	0.07	0.05	0.08	0.1
	nom	0.55	0.07	0.30	3.0	1.80	3.0	1.80				0.30	0.30	0.10	0.20				
	min	0.50	0.05	0.25	2.9	1.75	2.9	1.75				0.25	0.25	0.08	0.17				

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1068-1	---	---	---			08-02-13 08-02-26

Fig. 1. Package outline HUQFN16U (SOT1068-1)

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### 3. Legal information

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